RELIABILITY REPORT

FOR

MAX4993ELB+

PLASTIC ENCAPSULATED DEVICES

July 2, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX4993ELB+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX4991-MAX4994 low on-resistance analog switches operate from a single +1.8V to +5.5V supply. The MAX4991/MAX4993 feature a slow turn-on time to reduce clicks and pops due to coupling capacitors and audio amplifiers with a DC output bias. This feature provides click-and-pop reduction without adding additional parts for existing architectures. The MAX4991/MAX4992 are dual single-pole/double-throw (SPDT) switches, while the MAX4993/MAX4994 are double-pole/double-throw (DPDT) switches. The MAX4993/MAX4994 feature an active-low enable input (active-low EN) that sets all the channels to high impedance and reduces supply current when driven high. These devices have 0.3 on-resistance and 0.004% THD+N to route high fidelity audio signals. The MAX4991-MAX4994 are available in space-saving 10-pin UTQFN (1.4mm x 1.8mm) package, and are specified for operation over the -40°C to +85°C extended temperature range.

II. Manufacturing Information

A. Description/Function:	Low R_{ON}, Dual-SPDT/Single-DPDT Analog Switches with Slow Turn-On Time
B. Process:	S4
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	Thailand
F. Date of Initial Production:	April 26, 2008

III. Packaging Information

A. Package Type:	10-pin uDFN
B. Lead Frame:	Substrate
C. Lead Finish:	Gold
D. Die Attach:	Non Conductive Epoxy
E. Bondwire:	Au (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Multi Layer Theta Ja:	198.6°C/W
K. Multi Layer Theta Jc:	122.1°C/W

IV. Die Information

A. Dimensions:	47 X 31 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Al/0.5%Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 47 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.8 \times 10^{-9}$

$\lambda = 22.8$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the S4 Process results in a FIT Rate of 4.6 @ 25C and 79.2 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AJ33-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA, 1.5x VCCMax Overvoltage per JESD78.

Table 1
Reliability Evaluation Test Results

MAX4993ELB+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	47	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-55ºC/125ºC 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data